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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

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Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China











Spec No.: DS70-2001-027 Effective Date: 11/30/2016

Revision: E

LITE-ON DCC

RELEASE

BNS-OD-FC001/A4



1. DESCRIPTION

1.1 Features

- Isolation voltage between input and output V_{iso} : 5,000 V_{rms}
- 6pin DIP zero-cross optoisolators triac driver output
- High repetitive peak off-state voltage VDRM: Min. 800V
- High critical rate of rise of off-state voltage(dV/dt : MIN. 1000V / μs)
- Dual-in-line package: MOC3081 / MOC3082 / MOC3083
- Wide lead spacing package: MOC3081M / MOC3082M / MOC3083M
- Surface mounting package: MOC3081S / MOC3082S / MOC3083S
- Tape and reel packaging: MOC3081S-TA1 / MOC3082S-TA1 / MOC3083S-TA1
- Safety approval

UL 1577

cUL CA5A VDE DIN EN60747-5-5 (VDE 0884-5)

- **RoHS Compliance**
 - All materials be used in device are followed EU RoHS directive (No.2002/95/EC).
- MSL class1

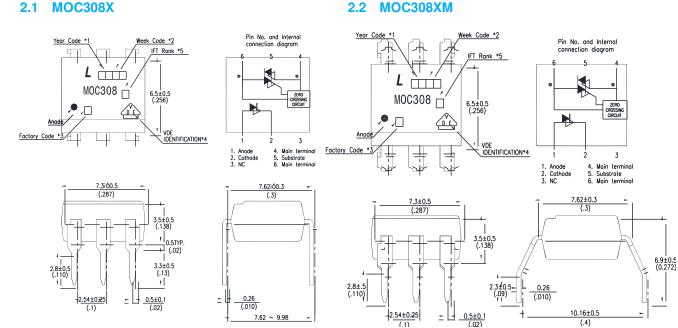
1.2 Applications

- **AC Motor Drives**
- **AC Motor Starters**
- E.M. Contactors
- **Lighting Controls**
- Solenoid/Valve Controls
- Solid State Relays
- Static Power Switches
- **Temperature Controls**

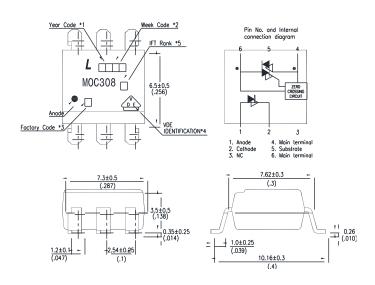


2. PACKAGE DIMENSIONS

MOC308X



2.3 MOC308XS



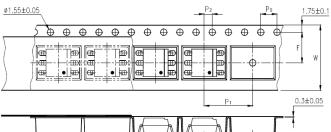
Notes:

- 1. Year date code.
- 2. 2-digit work week.
- 3. Factory identification mark shall be marked (W: China-CZ, Y: Thailand)
- 4. VDE option
- 5. IFT rank
- * Dimensions are in Millimeters and (Inches).

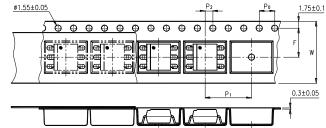


3. TAPING DIMENSIONS

3.1 MOC308XS-TA



3.2 MOC308XS-TA1



Description	Symbol	Dimension in mm (inch)		
Tape wide	W	16±0.3 (0.63)		
Pitch of sprocket holes	P ₀	4±0.1 (0.15)		
Distance of compartment	F	7.5±0.1 (0.295)		
Distance of compartment	P_2	2±0.1 (0.079)		
Distance of compartment to compartment	P ₁	12±0.1 (0.472)		

3.3 Quantities Per Reel

Package Type	MOC308XS series				
Quantities (pcs)	1000				



4. RATING AND CHARACTERISTICS

4.1 Absolute Maximum Ratings at Ta=25°C

	Parameter	Symbol	Rating	Unit
	Forward Current	I _F	50	mA
loout	Reverse Voltage	V_{R}	6	V
Input	Junction Temperature	T_J	125	°C
	Power Dissipation	Р	120	mW
	Off-State Output Terminal Voltage	V_{DRM}	800	V
Output	On-State RMS Current	I _{D(RMS)}	100	mA
	Peak Repetitive Surge Current (PW=1ms, 120pps)	I _{TSM}	1	Α
	Junction Temperature	TJ	125	°C
	Collector Power Dissipation	Pc	150	mW
	Total Power Dissipation	P _{tot}	250	mW
1.	Isolation Voltage	V_{iso}	5000	V_{rms}
	Operating Temperature	T_{opr}	-40 ~ +110	°C
	Storage Temperature	T_{stg}	-55 ~ +150	°C
2.	Soldering Temperature	T_{sol}	260	°C

1. AC For 1 Minute, R.H. = 40 ~ 60%

Isolation voltage shall be measured using the following method.

- (1) Short between anode and cathode on the primary side and between collector and emitter on the secondary side.
- (2) The isolation voltage tester with zero-cross circuit shall be used.
- (3) The waveform of applied voltage shall be a sine wave.
- 2. For 10 Seconds



4.2 ELECTRICAL OPTICAL CHARACTERISTICS at Ta=25°C

Parameter			Symb	Min.	Тур.	Max.	Unit	Test Condition	
11	Forward Voltage		V _F	_	1.2	1.4	٧	I _F =20mA	
Input	Reverse Current		I _R	_	0.05	10	μА	V _R =6V	
Peak Blocking Current, Either 1 Direction		I _{DRM}	_	_	500	nA	V _{DRM} = 800V		
Output	Peak On-State Voltage, Either Direction		V_{TM}	_	_	3.0	V	I _{TM} =100 mA Peak	
	Critical rate of Rise of Off-St 2 Voltage		Off-State	dv/dt	1000	—	—	V/μs	Vin=240Vrms
Couple	Led Trigger Current, Current Required to 3 Latch Output, Either	MOC3081		_	_	15			
		•	MOC3082	I _{FT}	_	_	10	mA	Main Terminal Voltage = 3V
		Direction	MOC3083		_	_	5		
	Holding Current, Either Direction		l _Η	_	400	_	μА		
ZERO CROSSING	Inhibit Voltage		V _{INH}	_	5	20	Volts	I _F =Rated I _{FT} , MT1-MT2 Voltage above which device will not trigger.	
	Leakage in Inhibited State		I _{DRM2}	_	_	500	μΑ	I_F = Rated I_{FT} , Rated V_{DRM} , Off State	

^{*1.} Test voltage must be applied within dv/dt rating.

^{*2.} This is static dv/dt. Commutating dv/dt is a function of the load-driving thyristor(s) only.

^{*3.} All devices are guaranteed to trigger at an I_F value less than or equal to max I_{FT}. Therefore, recommended operating I_F lies between max I_{FT}, 15 mA for MOC3081, 10 mA for MOC3082, 5 mA for MOC3083, and absolute max I_F (50mA).



5. CHARACTERISTICS CURVES (TYPICAL PERFORMANCE)

Fig.1 Forward Current vs.

Ambient Temperature

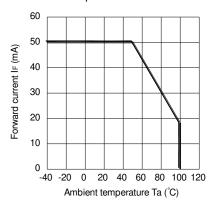


Fig.3 Minimum Trigger Current

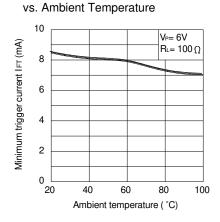


Fig.5 On-state Voltage vs. Ambient Temperature

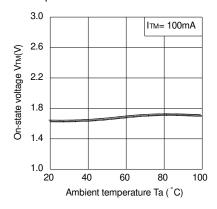


Fig.2 On-state Current vs. Ambient Temperature

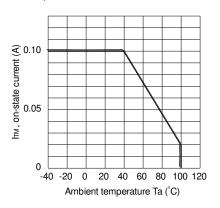


Fig.4 Forward Current vs. Forward Voltage

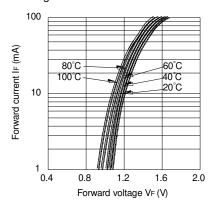


Fig.6 Holding Current vs.

Ambient Temperature

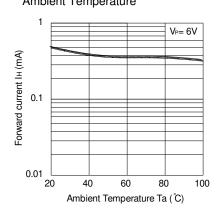




Fig. 7 Repetitive Peak Off-state Current vs. Temperature

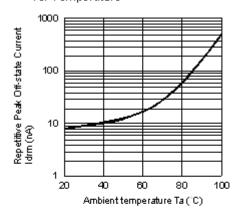
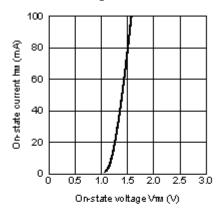
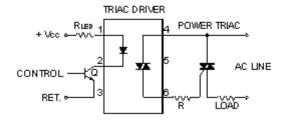


Fig. 8 On-state Current vs.

On-state Voltage



Basic Driver Circuit



Rues=(Voo-Vr LED-VsaQ)/ Irm R= Vp AC line/Iran

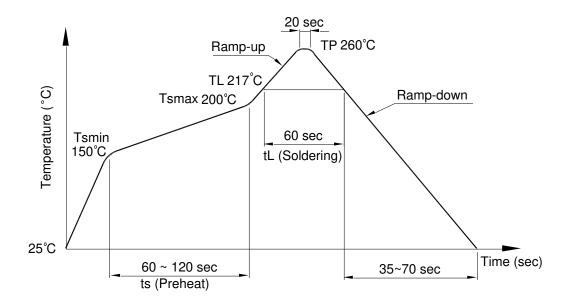


6. TEMPERATURE PROFILE OF SOLDERING

6.1 IR Reflow soldering (JEDEC-STD-020C compliant)

One time soldering reflow is recommended within the condition of temperature and time profile shown below. Do not solder more than three

Profile item	Conditions			
Preheat				
- Temperature Min (T _{Smin})	150°C			
- Temperature Max (T _{Smax})	200°C			
- Time (min to max) (ts)	90±30 sec			
Soldering zone				
- Temperature (T _L)	217°C			
- Time (t _L)	60 sec			
Peak Temperature (T _P)	260°C			
Ramp-up rate	3°C / sec max.			
Ramp-down rate	3~6°C / sec			







6.2 Wave soldering (JEDEC22A111 compliant)

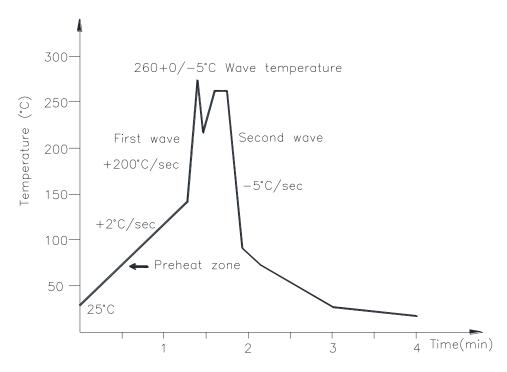
One time soldering is recommended within the condition of temperature.

Temperature: 260+0/-5°C

Time: 10 sec.

Preheat temperature:25 to 140°C

Preheat time: 30 to 80 sec.



6.3 Hand soldering by soldering iron

Allow single lead soldering in every single process. One time soldering is recommended.

Temperature: 380+0/-5°C

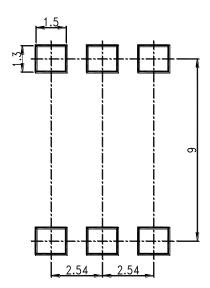
Time: 3 sec max.





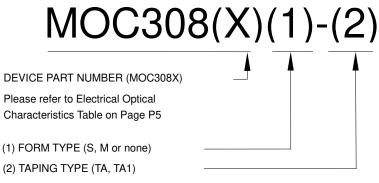
7. RRECOMMENDED FOOT PRINT PATTERNS (MOUNT PAD)

Unit: mm

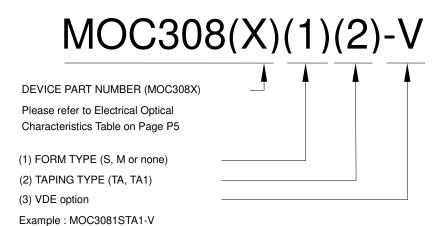




8. NAMING RULE



Example: MOC3081S-TA1



9. NOTES

- LiteOn is continually improving the quality, reliability, function or design and LiteOn reserves the right to make changes without further notices.
- The products shown in this publication are designed for the general use in electronic applications such as office automation equipment, communications devices, audio/visual equipment, electrical application and instrumentation.
- For equipment/devices where high reliability or safety is required, such as space applications, nuclear power control equipment, medical equipment, etc, please contact our sales representatives.
- When requiring a device for any "specific" application, please contact our sales in advice.
- If there are any questions about the contents of this publication, please contact us at your convenience.
- The contents described herein are subject to change without prior notice.
- Immerge unit's body in solder paste is not recommended.